Clock OSC SG5032VAN

Product name SG5032VAN 148.351600MHz KCBA
Product Number / Ordering code X1G0042610138xx

Please refer to the 9.Packing information about xx (last 2 digits)

Output waveform LVDS

Pb free / Complies with EU RoHS directive

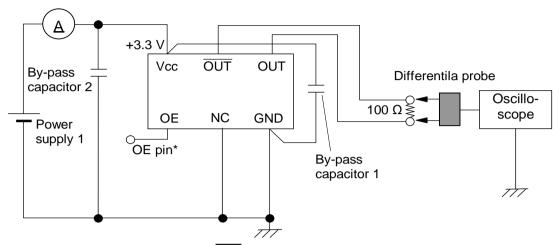
Reference weight Typ. 52 mg

| 1.Absolute maximum ratings | | | | | | | | |
|----------------------------|---------|------|------|---------|------|---------------------------|--|--|
| Parameter | Symbol | Min. | Тур. | Max. | Unit | Conditions / Remarks | | |
| Maximum supply voltage | Vcc-GND | -0.3 | - | +4 | V | - | | |
| Storage temperature | T_stg | -40 | - | +125 | °C | Storage as single product | | |
| Input voltage | Vin | -0.3 | - | Vcc+0.3 | V | OE Terminal | | |

| 2.Specifications(character Parameter | Symbol | Min. | Тур. | Max. | Unit | Conditions / Remarks | |
|---|------------------|----------|----------|----------|-------------------------|--|--|
| Output frequency | f0 | - | 148.3516 | - | MHz | Corrainerie / Homanie | |
| Supply voltage | Vcc | 2.25 | - | 3.63 | V | - | |
| Operating temperature | T_use | -20 | _ | +70 | °C | - | |
| Frequency tolerance | f tol | -20 | _ | 20 | x10 ⁻⁶ | - | |
| Current consumption | lcc | - | _ | 30 | mA | OE = Vcc, L_LVDS = 100 Ω | |
| Stand-by current | I std | - | - | - | mA | | |
| Disable current | I dis | - | - | 20.0 | mA | OE = GND | |
| Symmetry | SYM | 45 | _ | 55 | % | At output crossing point | |
| Output voltage(LVDS) | Vod | 250 | - | 450 | mV | - | |
| . , | dVop | - | - | 50 | mV | 1- | |
| | Vos | 1.15 | _ | 1.35 | V | 1- | |
| | dVos | - | _ | 150 | mV | 1- | |
| Output load condition(LVDS) | L LVDS | - | 100 | _ | Ω | Connected between OUT and OUT | |
| Input voltage | V _{IH} | 70 % Vcc | _ | - | | - | |
| | V _{IL} | - | _ | 30 % Vcc | | 1- | |
| Rise time | t _r | - | _ | 300 | ps | - | |
| Fall time | tf | - | - | 300 | ps | - | |
| Start-up time | t_str | - | - | 3 | ms | - | |
| Jitter | t _{DJ} | - | 5 | - | ps | Deterministic Jitter Vcc=2.5V | |
| | T _{RJ} | - | 1 | - | ps | Random Jitter Vcc=2.5V | |
| | t _{RMS} | - | 5.2 | - | ps | δ(RMS of total distribution) Vcc=2.5V | |
| | t _{p-p} | - | 22.2 | - | ps | Peak to Peak Vcc=2.5V | |
| | t _{acc} | - | 1 | - | ps | Accumulated Jitter(δ) n=2 to 50000 cycles Vcc=2.5V | |
| Phase jitter | t _{PJ} | - | 0.31 | - | ps | Offset Frequency: 12kHz to 20MHz Vcc=2.5V | |
| Phase noise | L(f) | - | -49 | - | dBc/Hz | Offset 1Hz Vcc=2.5V | |
| | | - | -81 | - | dBc/Hz | Offset 10Hz Vcc=2.5V | |
| | | - | -107 | - | dBc/Hz | Offset 100Hz Vcc=2.5V | |
| | | - | -121 | - | dBc/Hz | Offset 1kHz Vcc=2.5V | |
| | | - | -131 | - | dBc/Hz | Offset 10kHz Vcc=2.5V | |
| | | - | -137 | - | dBc/Hz | Offset 100kHz Vcc=2.5V | |
| | | - | -138 | - | dBc/Hz | Offset 1MHz Vcc=2.5V | |
| Frequency aging | f_age | -5 | - | 5 | x10 ⁻⁶ /Year | 25 °C, 1st year | |
| | | - | - | _ | | - | |

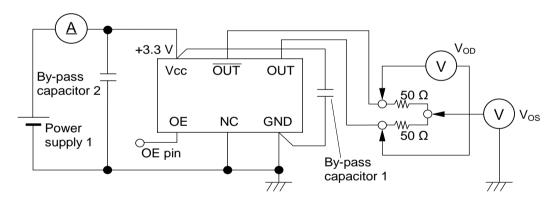
3.Test circuit

1) To observe waveform and current (case 1)



- * The lines from OUT and OUT pin are same length.
- * To measure the disable current, OE pin is connected to GND

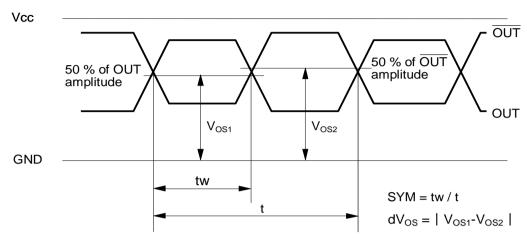
2) To observe waveform and current (case 2)



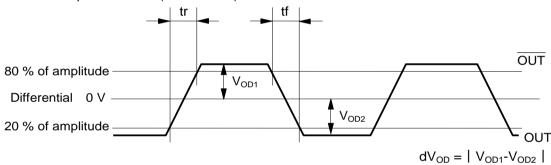
- * The lines from OUT and OUT pin are same length.
- 3) Measurement condition
- A) Oscilloscope
- •Bandwidth should be 5 times higher than DUT's output frequency (4 GHz).
- •Probe ground should be placed closely from test point and lead length should be as short as possible.
- B) By-pass capacitor 1 (approx. 0.01 μF to 0.1 μF) places closely between Vcc and GND.
- C) By-pass capacitor 2 (approx. 10 μF) places closely between power supply terminals on the board.
- D) Use the current meter whose internal impedance value is small.
- E) Power supply
- Start up time (0 Vg90 %Vcc) of power source should be more than 150 μ s and slew rate should be less than 19.8 mV/ μ s.
- Impedance of power supply should be as low as possible.

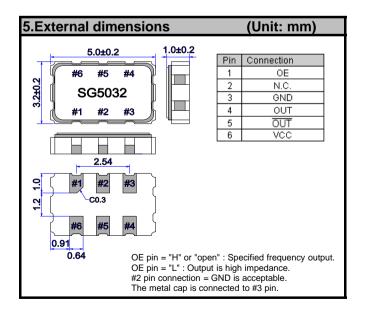
4. Timing chart

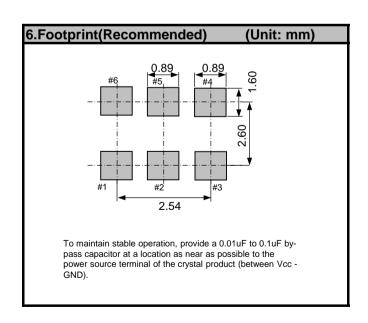
Each output waveform (OUT, and OUT)

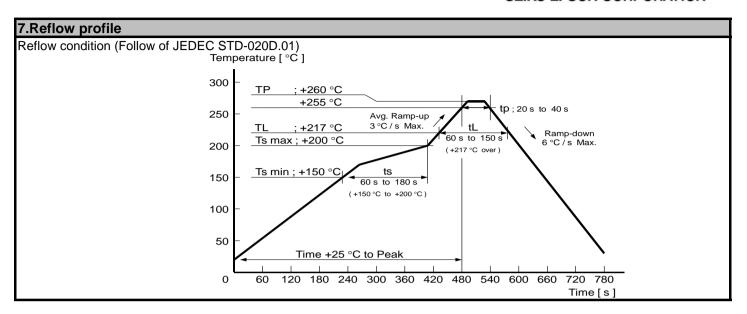


Differential output waveform (OUT - OUT)







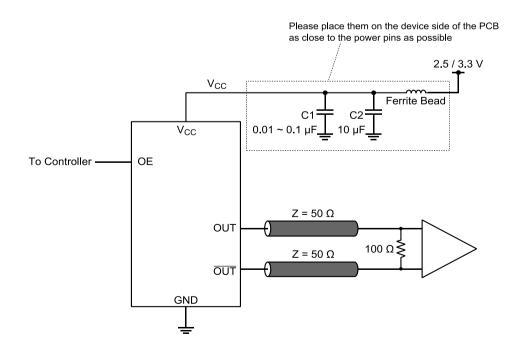


8. Example of schematic layout

This figure shows an example of this product's application schematic.

As with any high speed analog circuitry, the power supply pins for this device are vulnerable to noise. In order to achieve optimum jitter performance, power isolation with filter device is required for power supply pins.

In order to achieve best performance of the power isolation filter, it is recommended that the filter composing devices is placed on the device side of the PCB as close to the power pins as possible. The component value of this filter is just an example, it may have to be adjusted.



- * By-pass capacitor (approx. 0.01 μF to 0.1 $\mu F)$ places closely between Vcc and GND. * By-pass capacitor (approx. 10 $\mu F)$ places closely between power supply terminals on the board. * Please design the two output lines by characteristic impedance 100 Ω and same length, and try to make the output lines as short as possible.

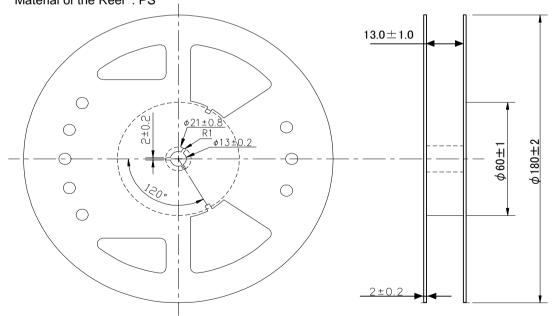
| 9.Packing | Packing information | | | | | | | |
|-----------|---------------------|-----------------------------------|------------------------------|----------------|--|--|--|--|
| [1]Produc | t number la | ast 2 digits code(xx) description | The recommended code is "00" | | | | | |
| | X1G0042 | 2610138xx | | | | | | |
| | Code | Condition | Code | Condition | | | | |
| | 01 | Any Q'ty vinyl bag(Tape cut) | 13 | 500pcs / Reel | | | | |
| | 11 | Any Q'ty / Reel | 00 | 1000pcs / Reel | | | | |
| | 12 | 250pcs / Reel | | | | | | |

SEIKO EPSON CORPORATION [2] Taping specification Subject to EIA-481 & IEC-60286 (1) Tape dimensions Material of the Carrier Tape: PS Material of the Top Tape : PET+PE Unit: mm 0 0 0 0 0 Carrier tape Top tape

| I | Symbol | Α | В | С | D | E | F | G | Н |
|---|--------|---------|---------|---------|----------|----------|----------|---------|---------|
| | Value | φ1.5 | 4.0±0.1 | 8.0±0.1 | 7.25±0.2 | 12.0±0.2 | 1.40±0.1 | 3.5±0.1 | 5.4±0.1 |
| | | +0.1/-0 | | | | | | | |

(2) Reel dimensions

Center material : PS Material of the Reel: PS



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